

Cervoz Industrial Embedded Module

Half Slim

Momentum Series (MLC)

M310 Family

Product Datasheet



Date: 2015.04.13

Revision: 1.1

File: Cervoz_Industrial_Embedded_Module_Half_Slim_M310_Datasheet_Rev1.1

Revision History

Date	Revision	Description
2015.03.13	1.0	First Released
2015.04.13	1.1	TeraByte Written (TBW) Information Added

Table of Contents

1. Product Overview.....	4
1.1 Introduction.....	4
1.2 Feature.....	4
1.3 Product Appearance & Models.....	5
2. Product Specifications.....	6
2.1 General Specifications.....	6
2.2 Electronic Specifications.....	7
2.2.1 Block Diagram.....	7
2.2.2 Pin Assignment and Descriptions.....	8
2.3 Environmental Specifications.....	9
2.4 Mechanical Specifications.....	9
3. Supported Command.....	10
3.1 List of Command Sets.....	10
4. Part No. Decoder.....	11
4.1 Part No. Decoder.....	11~12

1. Product Overview

1.1 Introduction

Cervoz Industrial Half Slim Embedded Module M310 family is a Solid State Disk product that is in compliance with the SATA III standards. The device design is based on the 7pin for data segment and 15pin for power segment standards. The Half Slim Embedded Module M310 family fits in any 7+15 SATA sockets on a motherboard; it can be used for both booting or storage purposes.

M310 family uses superior quality preselected multi-level cell (MLC) NAND flash memory from the industry leading manufacturer Toshiba. This product includes both standard temperature range and wide temperature range options with various capacities to choose from.

M310 family offers outstanding performance and reliability; the product family is a perfect solution for price sensitive semi-industrial and general industrial applications.

1.2 Feature

- Compliant with SATA III 6.0Gb/s
- MLC NAND flash memory
- Capacity: 4GB ~ 256GB
- Operating as boot disk
- Product includes Standard Temperature range & Wide Temperature range
- Static and dynamic wear leveling
- Bad block management
- S.M.A.R.T. & TRIM command

1.3 Product Appearance & Models

Cervoz Industrial Half Slim Module M310



M310 Family Standard Temp. (0°C ~ 70°C) Model No.	M310 Family Wide Temp. (-40°C ~ 85°C) Model No.	Capacity
CIE-HSM310THT004GS	CIE-HSM310THT004GW	4GB
CIE-HSM310TIT008GS	CIE-HSM310TIT008GW	8GB
CIE-HSM310TIT016GS	CIE-HSM310TIT016GW	16GB
CIE-HSM310TIT032GS	CIE-HSM310TIT032GW	32GB
CIE-HSM310TJT064GS	CIE-HSM310TJT064GW	64GB
CIE-HSM310TKT128GS	CIE-HSM310TKT128GW	128GB
CIE-HSM310TLB256GS	CIE-HSM310TLB256GW	256GB

Please Note:

Since certain storage capacity has to be reserved for firmware and controller management purposes; the physical capacity of the SATA flash module will be approximately 92.5% of the indicated capacity. If you need to install an image that has the exact (or close to) the indicated size of the flash module, please choose your flash module with a greater capacity.

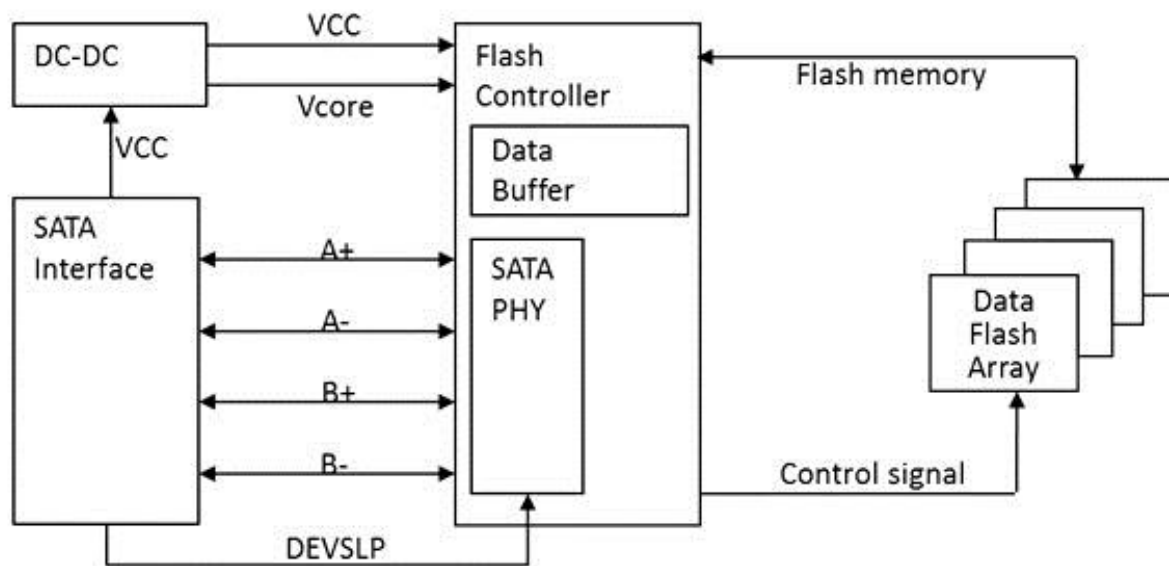
2. Product Specifications

2.1 General Specifications

Form Factor	Half Slim
Interface	SATA III 6.0Gb/s (backward compatible to 3.0Gb/s, 1.5Gb/s)
Connector	SATA (7+15pin)
NAND Flash Type	MLC
Capacity	4GB/8GB/16GB/32GB/64GB/128GB/256GB
Sequential Read	up to 510MB/s
Sequential Write	up to 190MB/s
ECC Scheme	up to 72bits / 1K Byte
MTBF	2,000,000 hours
TeraByte Written (TBW)	4GB : 4 8GB : 8 16GB : 16 32GB : 31 64GB : 63 128GB : 125 256GB : 250
Low Power Management	DEVSLP mode (Optional) DIPM/HIPM mode
Supply Voltage	+5.0V DC +/-5%
Power Consumption	Active mode: < 1960mW Idle mode: < 285mW DEVSLP mode: < 5mW
Dimension (LxWxH)	54.00*39.00*4.00mm

2.2 Electronic Specifications

2.2.1 Block Diagram



2.2.2 Pin Assignment



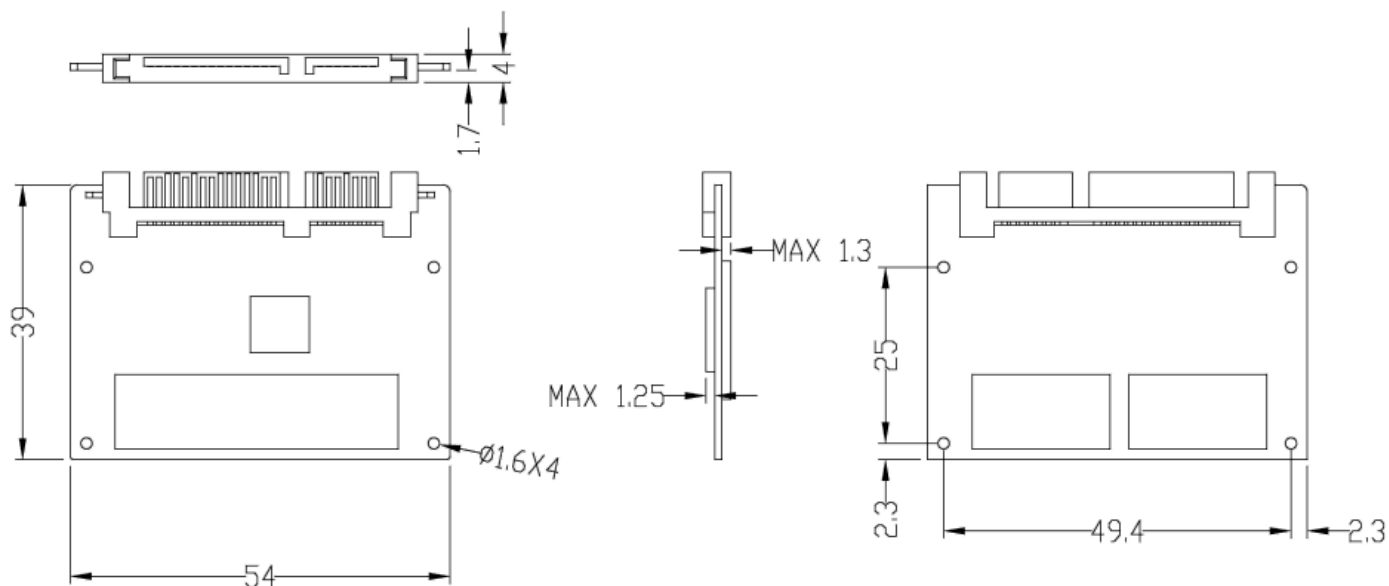
Group	Pin No.	Function	Description
Signal Segment	S1	GND	Ground
	S2	A+	Differential Signal Pair A
	S3	A –	Differential Signal Pair A
	S4	GND	Ground
	S5	B –	Differential Signal Pair B
	S6	B+	Differential Signal Pair B
	S7	GND	Ground
Key & Spacing			
Power Segment	P1	NC	Not Used (3.3V Power)
	P2	NC	Not Used (3.3V Power)
	P3	DEVSLP	Device Sleep Mode
	P4	GND	Ground
	P5	GND	Ground
	P6	GND	Ground
	P7	V5	5V Power, Pre-charge
	P8	V5	5V Power
	P9	V5	5V Power
	P10	GND	Ground
	P11	Reserved	Reserved
	P12	GND	Ground
	P13	NC	Not Used
	P14	NC	Not Used
	P15	NC	Not Used

2.3 Environmental Specifications

Type		Value
Temperature	Standard Temperature Operating:	0°C~70°C
	Standard Temperature Storage:	-40°C~85°C
	Wide Temperature Operating:	-40°C~85°C
	Wide Temperature Storage:	-50°C~95°C
Humidity	Operating & Storage	10~95%, Non-Condensing
Vibration	Operating	20G, 10Hz~2000Hz
Shock	Operating	1500G, 0.5ms

2.4 Mechanical Specifications

Type	Value
Form Factor	Half Slim
Length	54.00mm +/-0.15mm
Width	39.00mm +/-0.15mm
Thickness	4.00mm +/-0.15mm



3. Supported Command

3.1 List of Command Sets

Code	Description	Code	Description
00h	NOP	97h	IDLE
06h	Data Set Management	98h	CHECK POWER MODE
10h-1Fh	Recalibrate	99h	SLEEP
20h	Read Sectors	B0h	SMART
21h	Read Sectors without Retry	B1h	DEVICE CONFIGURATION
24h	Read Sectors EXT	C4h	Read Multiple
25h	Read DMA EXT	C5h	Write Multiple
27h	Read Native Max Address EXT	C6h	Set Multiple Mode
29h	Read Multiple EXT	C8h	Read DMA
2Fh	Read Log EXT	C9h	Read DMA without Retry
30h	Write Sectors	CAh	Write DMA
31h	Write Sectors without Retry	CBh	Write DMA without Retry
34h	Write Sectors EXT	CEh	Write Multiple FUA EXT
35h	Write DMA EXT	E0h	Standby Immediate
37h	Set Native Max Address EXT	E1h	Idle Immediate
38h	CFA WRITE SECTORS WITHOUT ERASE	E2h	Standby
39h	Write Multiple EXT	E3h	Idle
3Dh	Write DMA FUA EXT	E4h	Read Buffer
3Fh	Write Long EXT	E5h	Check Power Mode
40h	Read Verify Sectors	E6h	Sleep
41h	Read Verify Sectors without Retry	E7h	Flush Cache
42h	Read Verify Sectors EXT	E8h	Write Buffer
45h	WRITE UNCORRECTABLE EXT	EAh	Flush Cache EXT
60h	Read FPDMA Queued	ECh	Identify Device
61h	Write FPDMA Queued	EFh	Set Features
70h-7Fh	Seek	F1h	Security Set Password
90h	Execute Device Diagnostic	F2h	Security Unlock
91h	Initialize Device Parameters	F3h	Security Erase Prepare
92h	Download Microcode	F4h	Security Erase Unit
93h	DOWNLOAD MICROCODE DMA	F5h	Security Freeze Lock
94h	STANDBY IMMEDIATE	F6h	Security Disable Password
95h	IDLE IMMEDIATE	F8h	Read Native Max Address
96h	STANDBY	F9h	Set Max Address

4. Part No. Decoder

4.1 Part No. Decoder

1	-	2	3	4	5	6	7	8	9
Product Line	-	Form Factor	Product Series	Cervoz Family Code (Bus / Internal Control)	Flash Brand	Flash Capacity	Die Package	Module Capacity	Operating Temp.
XXX	-	XX	X	XXX	X	X	X	XXXX	X

1. Product Line

CIS	Cervoz Industrial SSD
CIM	Cervoz Industrial Memory Card
CIE	Cervoz Industrial Embedded Module

2. Form Factor

2S	2.5" SATA
2P	2.5" PATA
CF	CompactFlash
CA	CFast
MS	mSATA
HS	Half Slim
0V	PATA Disk 40pin Vertical
4V	PATA Disk 44pin Vertical
7T	SATA Disk 7pin Vertical Tall

3. Product Series

S	Supreme Series (SLC)
R	Reliance Series (RO-MLC)
M	Momentum Series (MLC)

4. Cervoz Family Code

Bus and Internal Control for Cervoz Product Families

5. Flash Brand

M	Micron
T	Toshiba

6. Flash Capacity

A	256Mb
B	512Mb
C	1Gb
D	2Gb
E	4Gb
F	8Gb
G	16Gb
H	32Gb
I	64Gb

J	128Gb
K	256Gb
L	512Gb
M	1Tb

7. Die Package

T	TSOP
B	BGA

8. Module Capacity

128M	128MB
256M	256MB
512M	512MB
001G	1GB
002G	2GB
004G	4GB
008G	8GB
016G	16GB
032G	32GB
064G	64GB
128G	128GB
256G	256GB
512G	512GB

9. Operating Temperature

S	Standard Grade (0~ +70°C)
W	Wide Temperature Grade (-40 ~ +85°C)